6 Channel EMI Pi-Filter Array with ESD Protection

This device is a 6 channel EMI filter array for data lines. Greater than -35 dB attenuation is obtained at frequencies from 800 MHz to 2.2 GHz. It also offers ESD protection - clamping transients from static discharges to protect delicate data line circuitry.

Features

- EMI Filtering and ESD Protection for Data Lines
- Integration of 30 Discretes Offers Cost and Space Savings
- Exceeds IEC61000-4-2 (Level 4) Specifications
- Low Profile Flip Chip Packaging
- MSL 1

Typical Applications

- EMI Filtering and ESD Protection for Data Lines
- Cell Phones
- Handheld Portables
- Notebook Computers
- MP3 Players

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

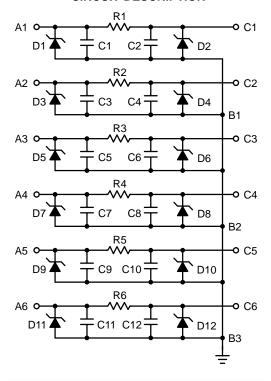
Rating	Symbol	Value	Unit
ESD Discharge IEC61000-4-2, - Air Discharge - Contact Discharge Human Body Model	V _{PP}	30 30 16	kV
DC Power per Resistor	P _R	100	mW
DC Power per Package	P _T	600	mW
Junction Temperature	TJ	150	°C
Operating Temperature Range	T _{op}	-40 to +85	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C



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CIRCUIT DESCRIPTION





FLIP CHIP CASE 499D PLASTIC

DEVICE MARKING

NUF6105YYWW

NUF4105= Specific Device Code YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
NUF6105FCT1	Flip Chip	3000/Tape & Reel

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Characteristic	Min	Тур	Max	Unit
V _{BR}	$I_Z = 10 \text{ mA}$	6.0	7.0	8.0	V
I _R	V _{RM} = 3.3 V per line	-	-	0.1	μΑ
R _{I/O}	$I_R = 20 \text{ mA}$	80	100	120	Ω
C _{line}	$V_{R=} 2.5 \text{ V}, f = 1 \text{ MHz (Note 1)}$	-	53	-	pF

^{1.} Measured from Input/Output Pins to Ground

TYPICAL PERFORMANCE CURVES

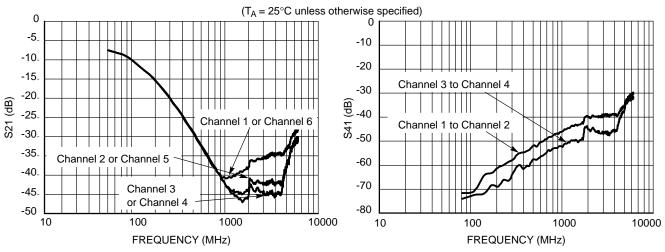


Figure 1. Insertion Loss Curve (S21 Measurement)

Figure 2. Analog Crosstalk Curve (S41 Measurement)

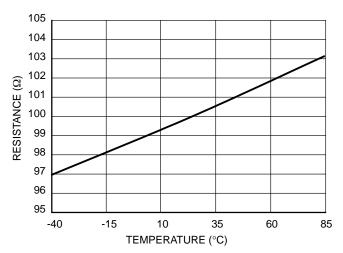


Figure 3. Resistance Over Temperature

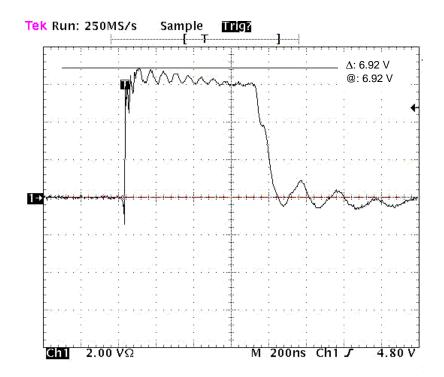


Figure 4. ESD Scope Trace Human Body Model (-8 kV)

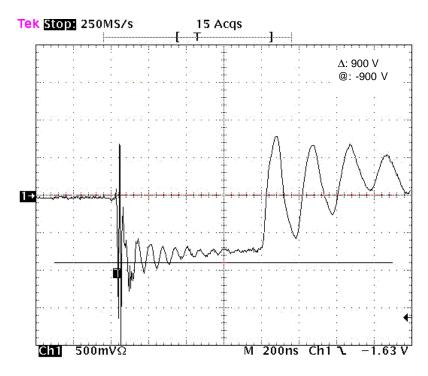


Figure 5. ESD Scope Trace Human Body Model (+8 kV)

Printed Circuit Board Recommendations

Parameter	500 μm Pitch 300 μm Solder Ball	
PCB Pad Size	250 μm +25 -0	
Pad Shape	Round	
Pad Type	NSMD	
Solder Mask Opening	350 μm ±25	
Solder Stencil Thickness	125 µm	
Stencil Aperture	250 x 250 μm sq.	
Solder Flux Ratio	50/50	
Solder Paste Type	No Clean Type 3 or Finer	
Trace Finish	OSP Cu	
Trace Width	150 μm Max	

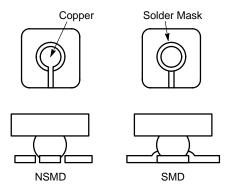


Figure 6. Solder Mask versus Non-Solder Mask Definition

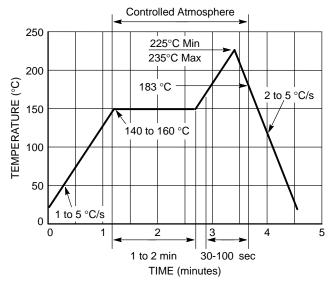
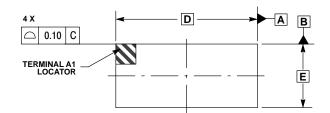


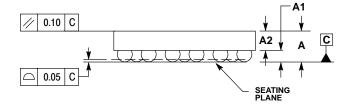
Figure 7. Solder Reflow Profile

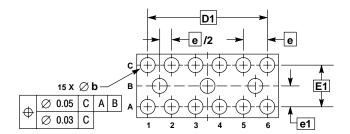
PACKAGE DIMENSIONS

15 PIN FLIPCHIP CSP

CASE 499D-01 ISSUE O







- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.700	
A1	0.210	0.270	
A2	0.380	0.430	
D	2.960 BSC		
E	1.330 BSC		
b	0.290	0.340	
е	0.500 BSC		
e1	0.435 BSC		
D1	2.500 BSC		
E1	0.870 BSC		

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